

Fig. 1

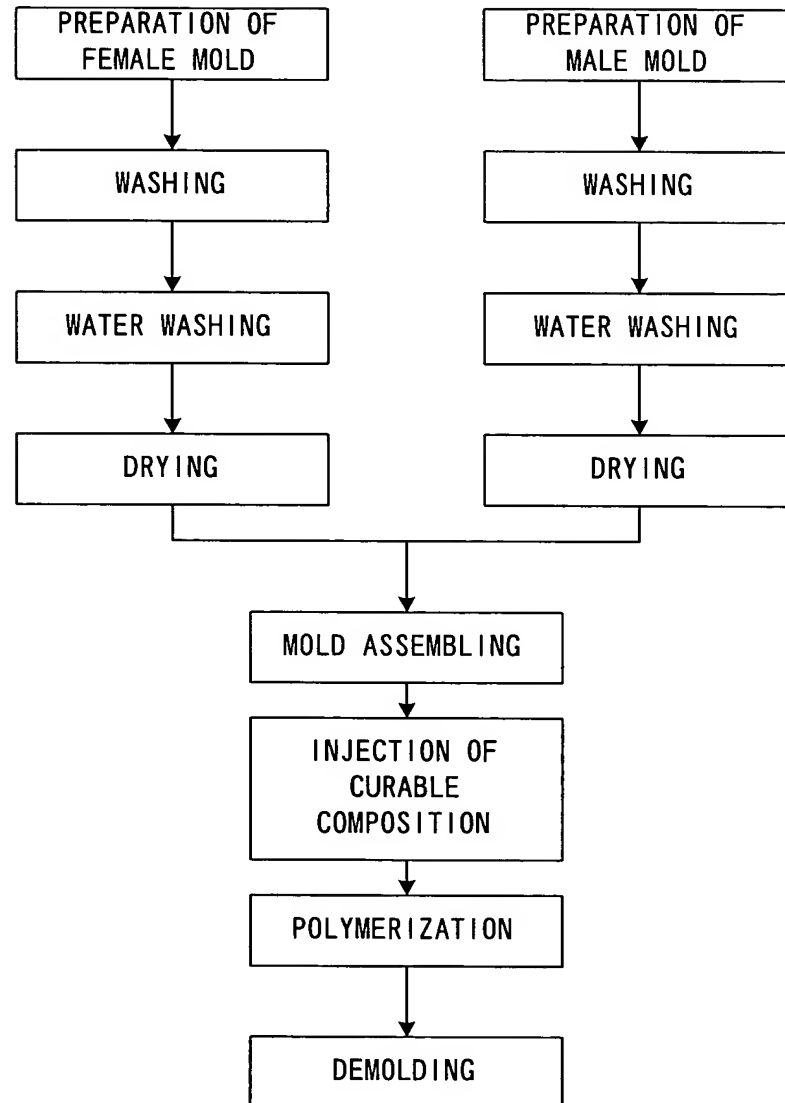


Fig. 2

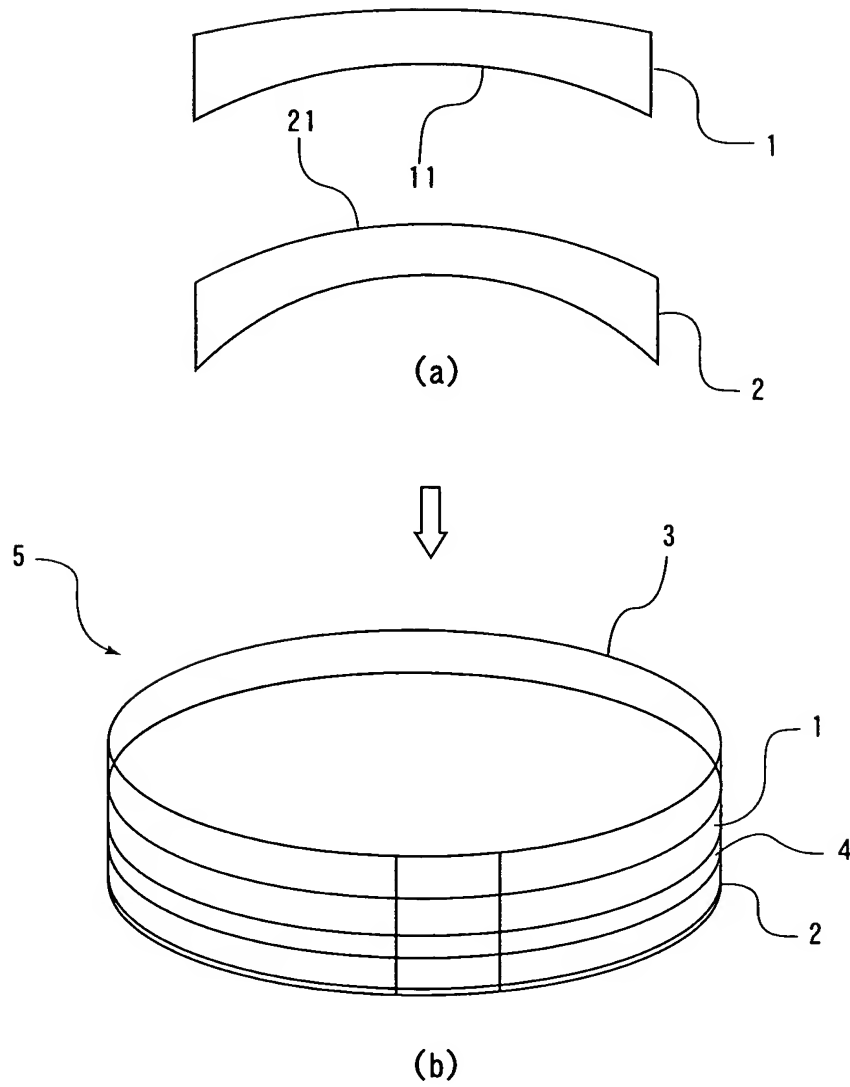


Fig. 3

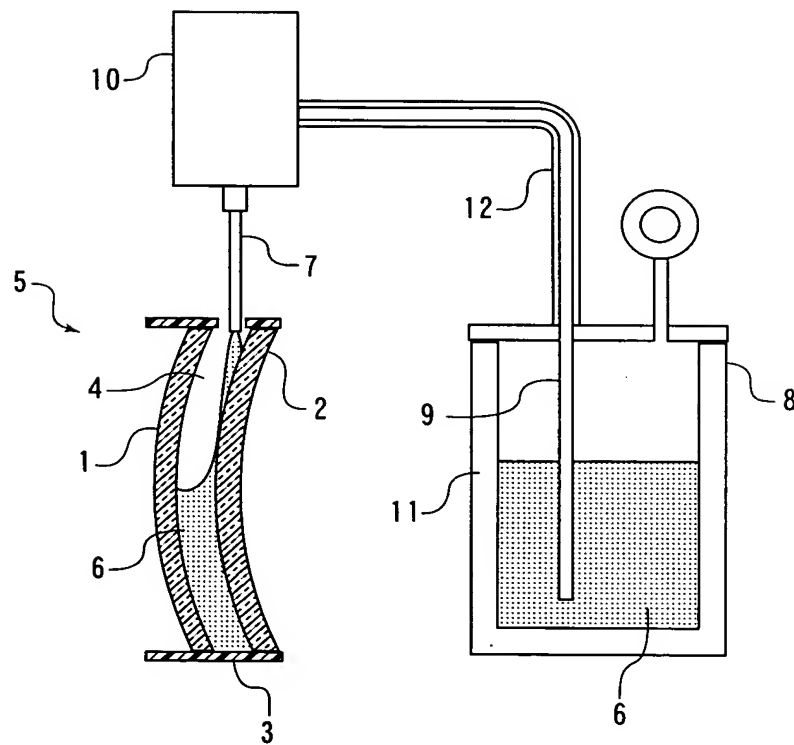


Figure 1 consists of two schematic diagrams, (a) and (b), illustrating a semiconductor device.

(a) Top view: A substrate 101 is shown with a grid of pillars 230 and 242. Circular regions 220 are located at the intersections of the pillars. A horizontal bar 501 is positioned above the pillars. Labels 1, 2, 220, 230, 242, and 520 are used to identify specific components.

(b) Cross-sectional view: This view shows the vertical structure of the pillars and circular regions. The pillars 230 and 242 are shown with a central core 1 and an outer layer 2. The circular regions 220 are also shown with a central core 1 and an outer layer 2. The horizontal bar 501 is shown in cross-section. Labels 1, 2, 220, 230, 242, and 520 are used to identify specific components.

Fig. 5

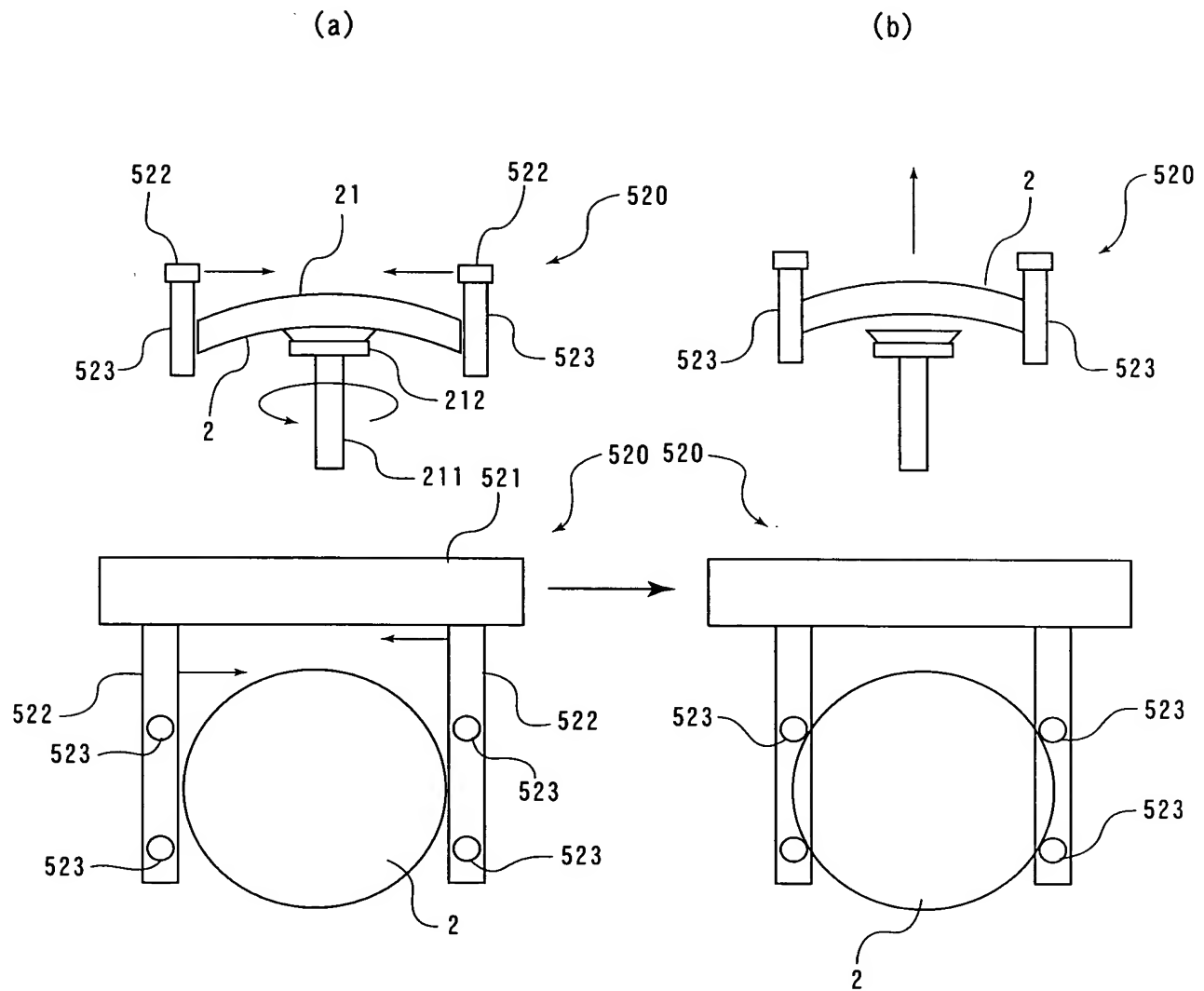
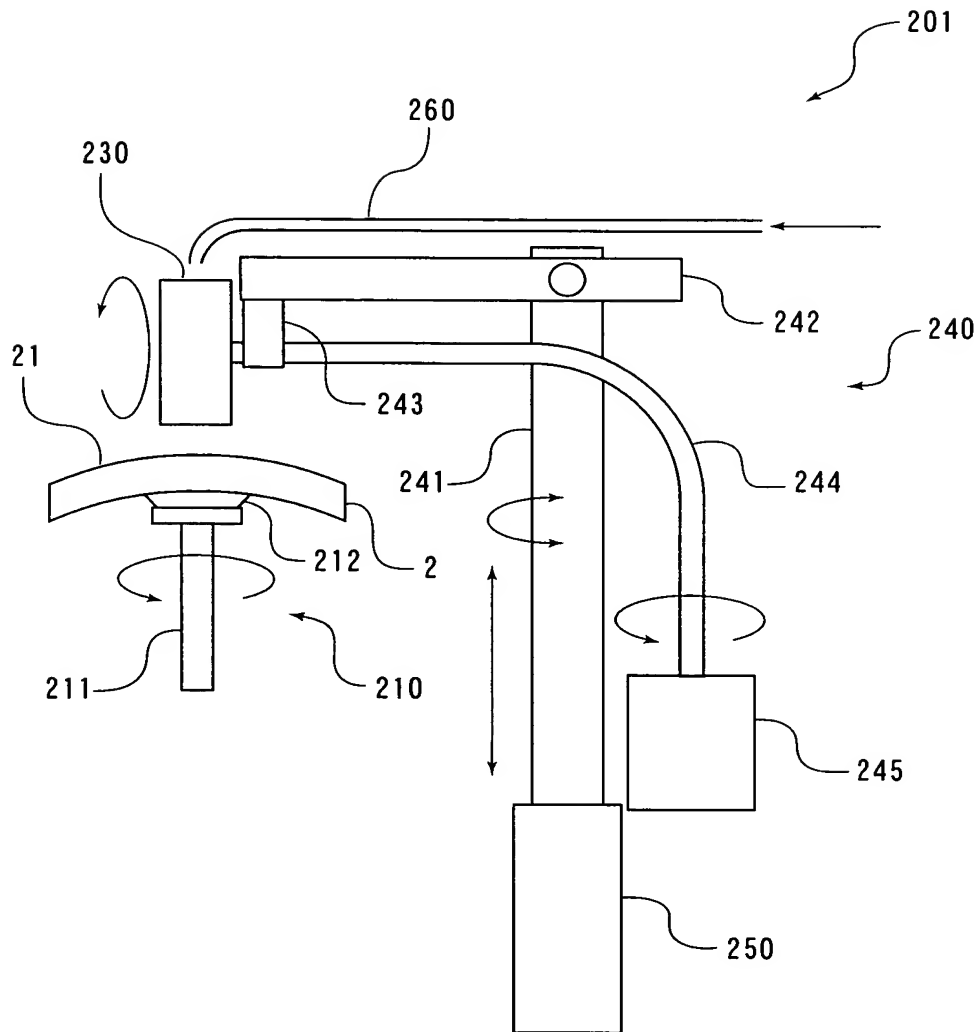


Fig. 6



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Fig. 7

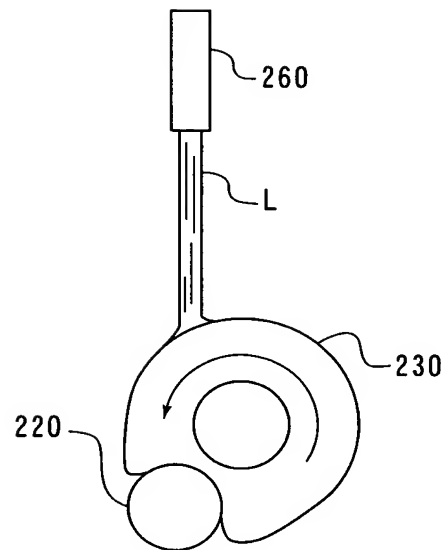
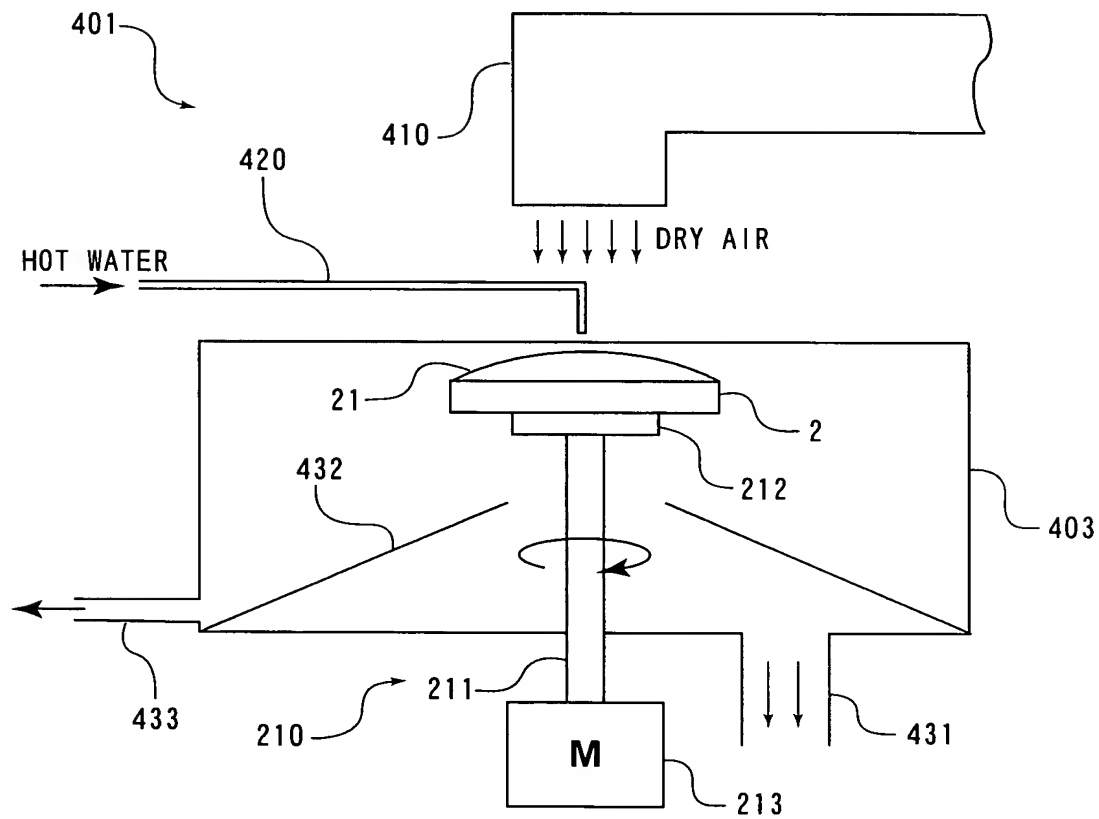


Fig. 8



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Fig. 9

